

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC3388EDD-1#PBF

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

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TOTAL MASS (g): 0.022745

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000880	1000000	38609.203125	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009711	975000	426044.15625	
		Iron (Fe)	7439-89-6	0.000239	24000	10507.6357422	
		Phosphorus (P)	7723-14-0	0.000003	300	131.895019531	
		Zinc (Zn)	7440-66-6	0.000007	700	307.7550354	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-99-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		<b>Lead Frame Total:</b>			<b>0.009960</b>	<b>1000000</b>	<b>437891.46875</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0	
		Exter. Plating Sn	7440-31-5	0.000455	1000000	20020.0234375	
		<b>External Plating Total:</b>			<b>0.000455</b>	<b>1000000</b>	<b>20020.0234375</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0	
		Inter. Plating Ag	7440-22-4	0.000225	1000000	9892.12597656	
		<b>Internal Plating Total:</b>			<b>0.000225</b>	<b>1000000</b>	<b>9892.12597656</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000229	750000	32257.4882812	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000176	250000	7737.84982031	
		<b>Die Attach Total:</b>			<b>0.000785</b>	<b>1000000</b>	<b>30995.328125</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)	0.001162	130000	59880.3359375
				Bromine (Br)	40099-09-8	0.000000	0
Silica (SiO2)	60676-86-0			0.009013	860000	396256.59375	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000000	0	0	
Carbon Black (C)	1333-86-4			0.000105	10000	4616.32519531	
<b>Encapsulation Total:</b>					<b>0.010480</b>	<b>1000000</b>	<b>460753.21875</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000040	1000000	1758.6009766	

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